

| External_Type  | Material_Group | Substances   | CAS_Number      | Mass          | Mass_Percentage_in_Leaf | Massmg        |
|----------------|----------------|--|-----------------|---------------|-------------------------|---------------|
| Die            | Doped silicon  | Silicon (Si)   | 7440-21-3       | 1.14          | 100.0                   | 3.9           |
|                |                |  | <b>Subtotal</b> | <b>1.14</b>   | <b>100</b>              | <b>3.9</b>    |
| Wire           | Pure metal     | Aluminium (Al)   | 7429-90-5       | 0.03          | 100.0                   | 0.12          |
|                |                |  | <b>Subtotal</b> | <b>0.03</b>   | <b>100</b>              | <b>0.12</b>   |
| Die Attach     | Lead alloy     | Tin (Sn)   | 7440-31-5       | 0.01          | 2.0                     | 0.02          |
|                | Lead alloy     | Silver (Ag)  | 7440-22-4       | 0.01          | 2.5                     | 0.03          |
|                | Lead alloy     | Lead (Pb)  | 7439-92-1       | 0.28          | 95.5                    | 0.95          |
|                |                |  | <b>Subtotal</b> | <b>0.3</b>    | <b>100</b>              | <b>1</b>      |
| Wire           | Pure metal     | Aluminium (Al)   | 7429-90-5       | 0.56          | 100.0                   | 1.9           |
|                |                |  | <b>Subtotal</b> | <b>0.56</b>   | <b>100</b>              | <b>1.9</b>    |
| Post-plating   | Pure metal     | Tin (Sn)   | 7440-31-5       | 3.5           | 100.0                   | 12            |
|                |                |  | <b>Subtotal</b> | <b>3.5</b>    | <b>100</b>              | <b>12</b>     |
| Lead Frame     | Copper alloy   | Phosphorous (P)  | 7723-14-0       | 0.02          | 0.03                    | 0.05          |
|                | Copper alloy   | Nickel (Ni) - cas no. 7440-02-0                        | 7440-02-0       | 0.02          | 0.03                    | 0.05          |
|                | Copper alloy   | Iron (Fe)  | 7439-89-6       | 0.05          | 0.1                     | 0.17          |
|                | Copper alloy   | Copper (Cu)  | 7440-50-8       | 50.79         | 99.84                   | 173.92        |
|                |                |  | <b>Subtotal</b> | <b>50.88</b>  | <b>100</b>              | <b>174.19</b> |
| Mould Compound | Polymer        | Phenol Formaldehyde resin (generic)                    | 9003-35-4       | 2.62          | 6.0                     | 8.96          |
|                | Polymer        | Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) | 25928-94-3      | 3.05          | 7.0                     | 10.45         |
|                | Filler         | Silica fused   | 60676-86-0      | 37.5          | 86.0                    | 128.4         |
|                | Carbon Black   | Carbon black   | 1333-86-4       | 0.44          | 1.0                     | 1.49          |
|                |                |  | <b>Subtotal</b> | <b>43.61</b>  | <b>100</b>              | <b>149.3</b>  |
|                |                |  | <b>Total</b>    | <b>100.02</b> | <b>100</b>              | <b>342.41</b> |

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